D OR N PACKAGE (TOP VIEW)

NC

IN- Π 4

IN+ [

REF

V<sub>CC</sub>-

CURR LIM [

CURR SENS [] 3

SLVS057D - AUGUST 1972 - REVISED JULY 1999

**I**I NC 14

12 [] V<sub>CC+</sub> 

9 🛛 V<sub>Z</sub> 8 [] NC

11

10

13 | FREQ COMP

**NOUTPUT** 

- 150-mA Load Current Without External **Power Transistor**
- **Adjustable Current-Limiting Capability**
- Input Voltages up to 40 V
- Output Adjustable From 2 V to 37 V
- Direct Replacement for Fairchild µA723C

## description

The µA723 is a precision integrated-circuit voltage regulator, featuring high ripple rejection,

excellent input and load regulation, excellent temperature stability, and low standby current. The circuit consists of a temperature-compensated reference-voltage amplifier, an error amplifier, a 150-mA output transistor, and an adjustable-output current limiter.

The μA723 is designed for use in positive or negative power supplies as a series, shunt, switching, or floating regulator. For output currents exceeding 150 mA, additional pass elements can be connected as shown in Figures 4 and 5.

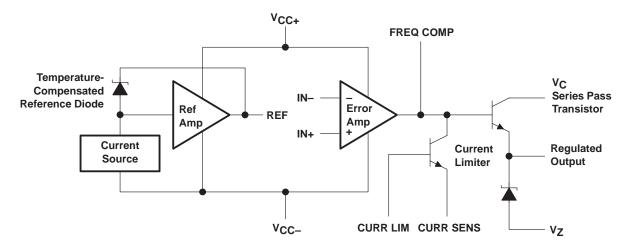
The μA723C is characterized for operation from 0°C to 70°C.

#### **AVAILABLE OPTIONS**

	PACKAGE	D DEVICES	CHIP
ТА	PLASTIC DIP (N)	DIP OUTLINE (N) (D)	
0°C to 70°C	μΑ723CN	μΑ723CD	μΑ723Y

The D package is available taped and reeled. Add the suffix R to the device type (e.g., µA723CDR). Chip forms are tested at 25°C.

## functional block diagram

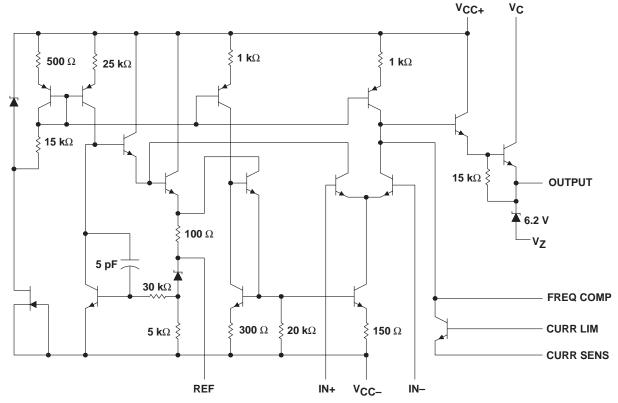




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### schematic



Resistor and capacitor values shown are nominal.

# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Peak voltage from $V_{CC+}$ to $V_{CC-}$ ( $t_w \le 50$ ms)	50 V
Continuous voltage from V <sub>CC+</sub> to V <sub>CC-</sub>	40 V
Input-to-output voltage differential	40 V
Differential input voltage to error amplifier	±5 V
Voltage between noninverting input and V <sub>CC</sub>	8 V
Current from V <sub>Z</sub>	25 mA
Current from REF	15 mA
Package thermal impedance, θ <sub>JA</sub> (see Notes 1 and 2): D package	86°C/W
N package	101°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package	260°C
Storage temperature range, T <sub>stq</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can impact reliability.
  - 2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



## recommended operating conditions

		MIN	MAX	UNIT
Input voltage, V <sub>I</sub>		9.5	40	V
Output voltage, VO		2	37	V
Input-to-output voltage differential, V <sub>C</sub> – V <sub>O</sub>		3	38	V
Output current, IO			150	mA
Operating free-air temperature range, TA	μΑ723C	0	70	°C

## electrical characteristics at specified free-air temperature (see Notes 3 and 4)

PARAMETER	TEST CONDIT	IONE	TA	ļ	ս <b>A723C</b>		UNIT	
PARAMETER	TEST CONDIT	TEST SONDITIONS				MAX	UNIT	
	$V_{I} = 12 \text{ V to } V_{I} = 15 \text{ V}$	25°C		0.1	1			
Input regulation	$V_{I} = 12 \text{ V to } V_{I} = 40 \text{ V}$		25°C		1	5	mV/V	
	$V_{I} = 12 \text{ V to } V_{I} = 15 \text{ V}$		0°C to 70°C			3		
Ripple rejection	f = 50 Hz to 10 kHz,	C <sub>ref</sub> = 0	25°C		74		dB	
Kippie rejection	f = 50 Hz to 10 kHz,	$C_{ref} = 5 \mu F$	25°C		86		aв	
Output regulation			25°C		-0.3	-2	mV/V	
Output regulation			0°C to 70°C			-6	IIIV/V	
Reference voltage, V <sub>ref</sub>			25°C	6.8	7.15	7.5	V	
Standby current	V <sub>I</sub> = 30 V,	I <sub>O</sub> = 0	25°C		2.3	4	mA	
Temperature coefficient of output voltage			0°C to 70°C		0.003	0.015	%/°C	
Short-circuit output current	$R_{SC} = 10 \Omega$ ,	VO = 0	25°C		65		mA	
Output noise voltage	BW = 100 Hz to 10 kHz,	C <sub>ref</sub> = 0	25°C		20	/		
Output noise voitage	BW = 100 Hz to 10 kHz,	$C_{ref} = 5 \mu F$	25°C		2.5		μV	

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier  $\leq$  10 k $\Omega$ . Unless otherwise specified, V<sub>I</sub> = V<sub>CC+</sub> = V<sub>C</sub> = 12 V, V<sub>CC-</sub> = 0, V<sub>O</sub> = 5 V, I<sub>O</sub> = 1 mA, R<sub>SC</sub> = 0, and C<sub>ref</sub> = 0.

4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

## electrical characteristics, T<sub>A</sub> = 25°C (see Notes 3 and 4)

PARAMETER	TEST CONDIT	IONE	μ		UNIT		
PARAMETER	TEST CONDIT	MIN	TYP	MAX	UNII		
Input regulation	V <sub>I</sub> = 12 V to V <sub>I</sub> = 15 V			0.1		mV/V	
Imput regulation	$V_{I} = 12 \text{ V to } V_{I} = 40 \text{ V}$			1		111 V / V	
Biople rejection	f = 50 Hz to 10 kHz,	$C_{ref} = 0$	74			dB	
Ripple rejection	f = 50 Hz to 10 kHz,	C <sub>ref</sub> = 5 μF	86			L GB	
Output regulation				-0.3		mV/V	
Reference voltage, V <sub>ref</sub>				7.15		V	
Standby current	V <sub>I</sub> = 30 V,	IO = 0		2.3		mA	
Short-circuit output current	$R_{SC} = 10 \Omega$	VO = 0		65		mA	
Output noise voltage	BW = 100 Hz to 10 kHz, $C_{ref} = 0$		20		\/		
Output hoise voltage	BW = 100 Hz to 10 kHz,	C <sub>ref</sub> = 5 μF		2.5		μV	

NOTES: 3. For all values in this table, the device is connected as shown in Figure 1 with the divider resistance as seen by the error amplifier  $\leq$  10 k $\Omega$ . Unless otherwise specified, V<sub>I</sub> = V<sub>CC+</sub> = V<sub>C</sub> = 12 V, V<sub>CC-</sub> = 0, V<sub>O</sub> = 5 V, I<sub>O</sub> = 1 mA, R<sub>SC</sub> = 0, and C<sub>ref</sub> = 0.

4. Pulse-testing techniques must be used that will maintain the junction temperature as close to the ambient temperature as possible.

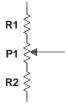


Table 1. Resistor Values ( $k\Omega$ ) for Standard Output Voltages

OUTPUT VOLTAGE	APPLICABLE FIGURES	FIXED C		OUTPUT ADJUSTABLE ±10% (SEE NOTE 6)				
(V)	(SEE NOTE 5)	R1 (kΩ)	R2 (kΩ)	R1 (kΩ)	P1 (kΩ)	P2 (kΩ)		
3.0	1, 5, 6, 9, 11, 12 (4)	4.12	3.01	1.8	0.5	1.2		
3.6	1, 5, 6, 9, 11, 12 (4)	3.57	3.65	1.5	0.5	1.5		
5.0	1, 5, 6, 9, 11, 12 (4)	2.15	4.99	0.75	0.5	2.2		
6.0	1, 5, 6, 9, 11, 12 (4)	1.15	6.04	0.5	0.5	2.7		
9.0	2, 4, (5, 6, 9, 12)	1.87	7.15	0.75	1.0	2.7		
12	2, 4, (5, 6, 9, 12)	4.87	7.15	2.0	1.0	3.0		
15	2, 4, (5, 6, 9, 12)	7.87	7.15	3.3	1.0	3.0		
28	2, 4, (5, 6, 9, 12)	21.0	7.15	5.6	1.0	2.0		
45	7	3.57	48.7	2.2	10	39		
75	7	3.57	78.7	2.2	10	68		
100	7	3.57	105	2.2	10	91		
250	7	3.57	255	2.2	10	240		
-6 (see Note 7)	3, 10	3.57	2.43	1.2	0.5	0.75		
-9	3, 10	3.48	5.36	1.2	0.5	2.0		
-12	3, 10	3.57	8.45	1.2	0.5	3.3		
-15	3, 10	3.57	11.5	1.2	0.5	4.3		
-28	3, 10	3.57	24.3	1.2	0.5	10		
-45	8	3.57	41.2	2.2	10	33		
-100	8	3.57	95.3	2.2	10	91		
-250	8	3.57	249	2.2	10	240		

NOTES: 5. The R1/R2 divider can be across either V<sub>O</sub> or V<sub>(ref)</sub>. If the divider is across V<sub>(ref)</sub>, use the figure numbers without parentheses. If the divider is across V<sub>O</sub> use the figure numbers in parentheses

VO, use the figure numbers in parentheses.
To make the voltage adjustable, the R1/R2 divider shown in the figures must be replaced by the divider shown below.



## **Adjustable Output Circuit**

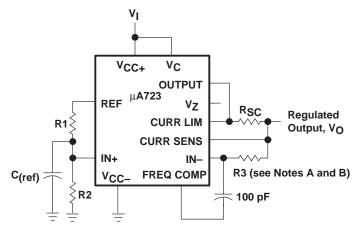
7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between  $V_{CC+}$  and  $V_{CC-}$  when  $V_O$  is equal to or more positive than -9 V.



**Table 2. Formulas for Intermediate Output Voltages** 

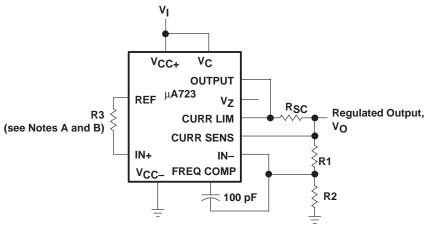
OUTPUTS FROM 2 V TO 7 V SEE FIGURES 1, 5, 6, 9, 11, 12 (4) AND NOTE 5	OUTPUTS FROM 4 V TO 250 V SEE FIGURE 7 AND NOTE 5	CURRENT LIMITING
$V_{O} = V_{(ref)} \times \frac{R2}{R1 + R2}$	$V_{O} = \frac{V_{(ref)}}{2} \times \frac{R2 - R1}{R1}$ R3 = R4	$I_{(limit)} \approx \frac{0.65 \text{ V}}{R_{SC}}$
OUTPUTS FROM 7 V TO 37 V SEE FIGURES 2, 4, (5, 6, 9, 11, 12) AND NOTE 5	OUTPUTS FROM -6 V TO -250 V SEE FIGURES 3, 8, 10 AND NOTES 5 AND 7	FOLDBACK CURRENT LIMITING SEE FIGURE 6
$V_{O} = V_{(ref)} \times \frac{R1 + R2}{R2}$	$V_{O} = -\frac{V_{(ref)}}{2} \times \frac{R1 + R2}{R1}$ $R3 = R4$	$I_{(knee)} \approx \frac{V_0 R3 + (R3 + R4) \ 0.65 \ V}{R_{SC} R4}$ $I_{OS} \approx \frac{0.65 \ V}{R_{SC}} \times \frac{R3 + R4}{R4}$

- NOTES: 5. The R1/R2 divider can be across either VO or V(ref). If the divider is across V(ref), use figure numbers without parentheses. If the divider is across V<sub>O</sub>, use the figure numbers in parentheses.
  - 7. For Figures 3, 8, and 10, the device requires a minimum of 9 V between V<sub>CC+</sub> and V<sub>CC-</sub> when V<sub>O</sub> is equal to or more positive than



NOTES: A. R3 =  $\frac{R1 \times R2}{R1 + R2}$  for a minimum  $\alpha_{V_0}$  B. R3 can be eliminated for minimum component count. Use direct connection (i.e., R<sub>3</sub> = 0).

Figure 1. Basic Low-Voltage Regulator ( $V_0 = 2 V \text{ to } 7 V$ )



NOTES: A. R3 =  $\frac{R1 \times R2}{R1 + R2}$  for a minimum  $\alpha_{V_0}$ B. R3 can be eliminated for minimum component count. Use direct connection (i.e., R<sub>3</sub> = 0).

Figure 2. Basic High-Voltage Regulator ( $V_0 = 7 \text{ V to } 37 \text{ V}$ )

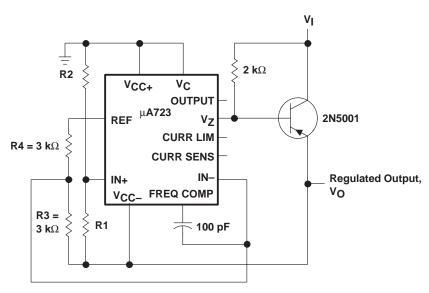


Figure 3. Negative-Voltage Regulator

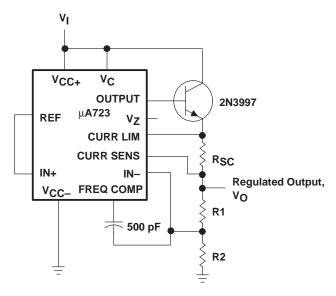


Figure 4. Positive-Voltage Regulator (External npn Pass Transistor)

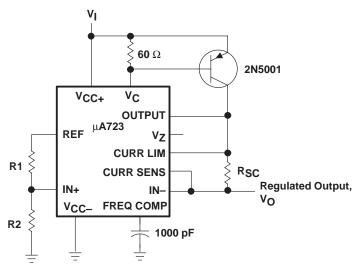


Figure 5. Positive-Voltage Regulator (External pnp Pass Transistor)

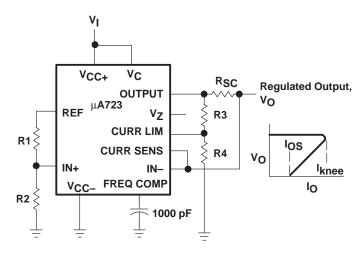


Figure 6. Foldback Current Limiting

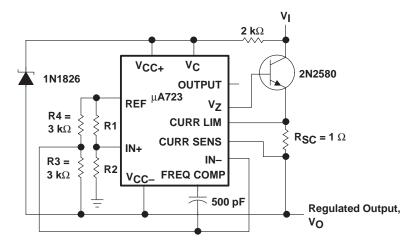


Figure 7. Positive Floating Regulator

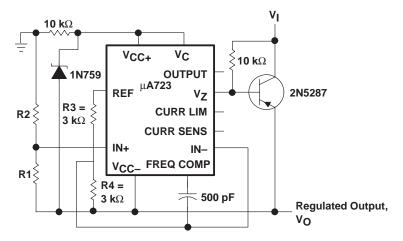
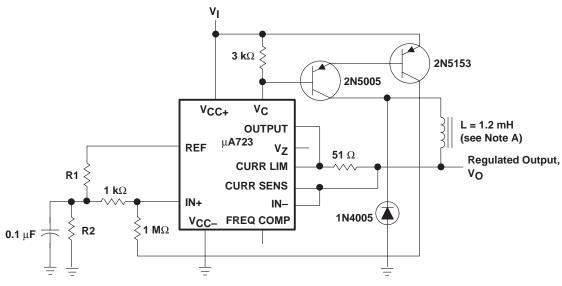
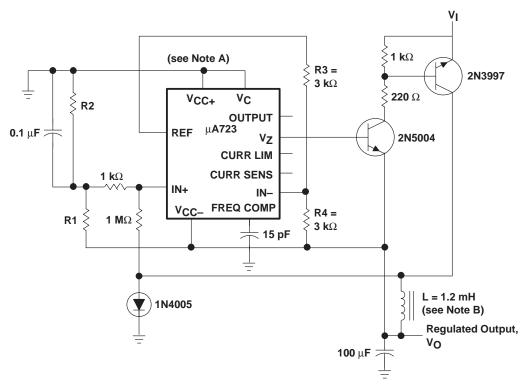


Figure 8. Negative Floating Regulator



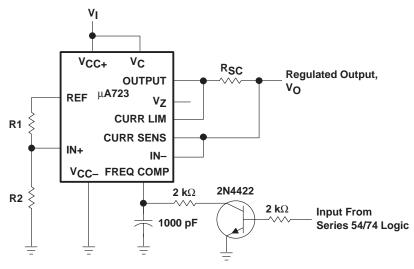
NOTE A: Lis 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

Figure 9. Positive Switching Regulator



- NOTES: A. The device requires a minimum of 9 V between  $V_{CC+}$  and  $V_{CC-}$  when  $V_O$  is equal to or more positive than -9 V.
  - B. L is 40 turns of No. 20 enameled copper wire wound on Ferroxcube P36/22-3B7 potted core, or equivalent, with a 0.009-inch air gap.

Figure 10. Negative Switching Regulator



NOTE A: A current-limiting transistor can be used for shutdown if current limiting is not required.

Figure 11. Remote Shutdown Regulator With Current Limiting



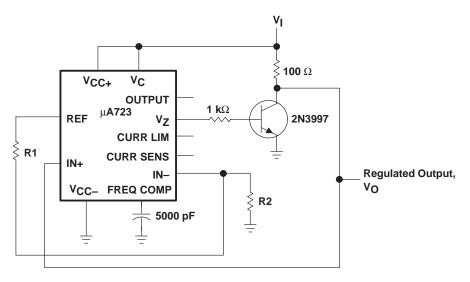


Figure 12. Shunt Regulator

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
UA723CD	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CD.A	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDE4	Active	Production	SOIC (D)   14	50   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDR	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDR.A	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDRE4	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CDRG4	Active	Production	SOIC (D)   14	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723C
UA723CN	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UA723CN
UA723CN.A	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UA723CN
UA723CNE4	Active	Production	PDIP (N)   14	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	UA723CN
UA723CNSR	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723
UA723CNSR.A	Active	Production	SOP (NS)   14	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UA723

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No. RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



## PACKAGE OPTION ADDENDUM

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# **PACKAGE MATERIALS INFORMATION**

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## TAPE AND REEL INFORMATION



# TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

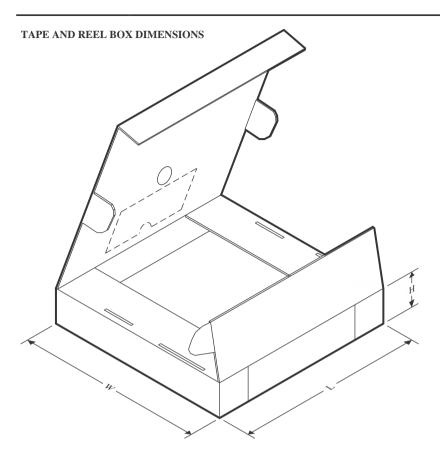
## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA723CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
UA723CNSR	SOP	NS	14	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1

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## \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA723CDR	SOIC	D	14	2500	353.0	353.0	32.0
UA723CNSR	SOP	NS	14	2000	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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## **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UA723CD	D	SOIC	14	50	506.6	8	3940	4.32
UA723CD.A	D	SOIC	14	50	506.6	8	3940	4.32
UA723CDE4	D	SOIC	14	50	506.6	8	3940	4.32
UA723CN	N	PDIP	14	25	506	13.97	11230	4.32
UA723CN.A	N	PDIP	14	25	506	13.97	11230	4.32
UA723CNE4	N	PDIP	14	25	506	13.97	11230	4.32



SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



## **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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